



## STD888T4

### Medium Current, High Performance, Low Voltage PNP Transistor

#### General features

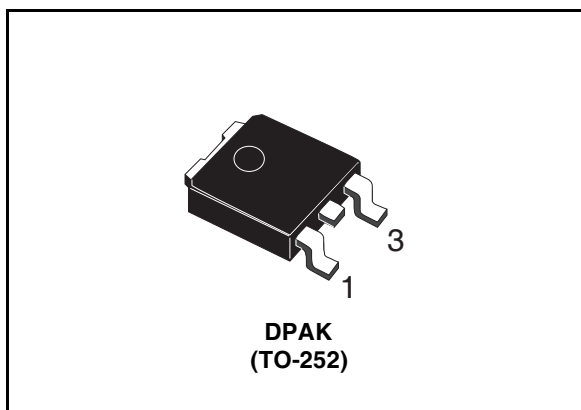
- Very low Collector to Emitter saturation voltage
- D.C. Current gain,  $h_{FE} > 100$
- 5A continuous collector current
- Surface mounting DPAK(TO-252) power package in tape & reel packing
- In compliance with the 2002/93/EC European Directive

#### Description

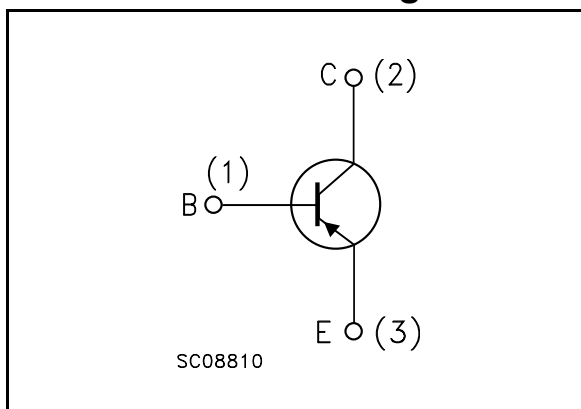
The device is manufactured in low voltage PNP Planar Technology by using a "Base Island" layout. The resulting transistor shows exceptional high gain performance coupled with very low saturation voltage.

#### Applications

- Power management in portable equipment
- Voltage regulation in bias supply circuits
- Switching regulator in battery charger applications
- Heavy load driver



#### Internal schematic diagram



#### Order codes

Part Number	Marking	Package	Packing
STD888T4	D888	DPAK	Tape & reel

# Contents

<b>1</b>	<b>Electrical ratings</b> .....	<b>3</b>
<b>2</b>	<b>Electrical characteristics</b> .....	<b>4</b>
2.1	Electrical characteristics (curves) .....	5
2.2	Test circuits .....	6
<b>3</b>	<b>Package mechanical data</b> .....	<b>7</b>
<b>4</b>	<b>Revision history</b> .....	<b>9</b>

# 1 Electrical ratings

**Table 1. Absolute maximum rating**

Symbol	Parameter	Value	Unit
$V_{CBO}$	Collector-base voltage ( $I_E = 0$ )	-45	V
$V_{CEO}$	Collector-emitter voltage ( $I_B = 0$ )	-30	V
$V_{EBO}$	Emitter-base voltage ( $I_C = 0$ )	-6	V
$I_C$	Collector current	-5	A
$I_{CM}$	Collector peak current ( $t_P < 5\text{ms}$ )	-10	A
$P_{tot}$	Total dissipation at $T_C = 25^\circ\text{C}$	15	W
$T_{stg}$	Storage temperature	-65 to 150	$^\circ\text{C}$
$T_J$	Max. operating junction temperature	150	$^\circ\text{C}$

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	8.33	$^\circ\text{C/W}$

## 2 Electrical characteristics

( $T_{case} = 25^{\circ}C$  unless otherwise specified)

**Table 3. Electrical characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{CBO}$	Collector cut-off current ( $I_E = 0$ )	$V_{CB} = -30V$ $V_{CB} = -30V; T_C = 100^{\circ}C$			-10 100	$\mu A$ $\mu A$
$I_{EBO}$	Emitter cut-off current ( $I_C = 0$ )	$V_{EB} = -6V$			-10	$\mu A$
$V_{(BR)CEO}^{(2)}$	Collector-emitter breakdown voltage ( $I_B = 0$ )	$I_C = -10mA$	-30			V
$V_{(BR)CBO}$	Collector-base breakdown voltage ( $I_E = 0$ )	$I_C = -100\mu A$	-45			V
$V_{(BR)EBO}$	Emitter-base breakdown voltage ( $I_C = 0$ )	$I_E = -100\mu A$	-6			V
$V_{CE(sat)}^{(2)}$	Collector-emitter saturation voltage	$I_C = -0.5A$ $I_B = -5mA$ $I_C = -2A$ $I_B = -50mA$ $I_C = -5A$ $I_B = -250mA$ $I_C = -6A$ $I_B = -250mA$ $I_C = -8A$ $I_B = -400mA$ $I_C = -10A$ $I_B = -500mA$			-0.15 -0.35 -0.7 -1 -1.2	V V V V V
$V_{BE(sat)}^{(2)}$	Base-emitter saturation voltage	$I_C = -2A$ $I_B = -50mA$ $I_C = -6A$ $I_B = -250mA$		-1.2	-1.1	V V
$h_{FE}^{(2)}$	DC current gain	$I_C = -10mA$ $V_{CE} = -1V$ $I_C = -500mA$ $V_{CE} = -1V$ $I_C = -5A$ $V_{CE} = -1V$ $I_C = -5A$ $V_{CE} = -1V$ $T_C = 100^{\circ}C$ $I_C = -8A$ $V_{CE} = -1V$ $I_C = -10A$ $V_{CE} = -1V$	120 100 70	200 200 100 100 55 35	300	
$t_d$ $t_r$ $t_s$ $t_f$	Resistive load Delay time Rise time Storage time Fall time	$I_C = -3A$ $V_{CC} = -20V$ $I_{B1} = -I_{B2} = -60mA$ (see figure 7)		180 160 250 80	220 210 300 100	ns ns ns ns

Note (2) Pulsed duration = 300  $\mu s$ , duty cycle  $\leq 1.5\%$

## 2.1 Electrical characteristics (curves)

Figure 1. DC current gain

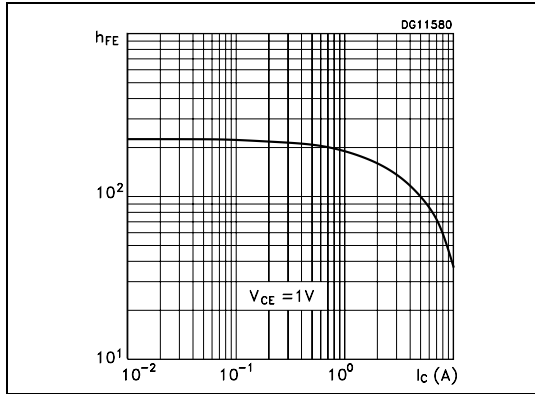


Figure 2. DC current gain

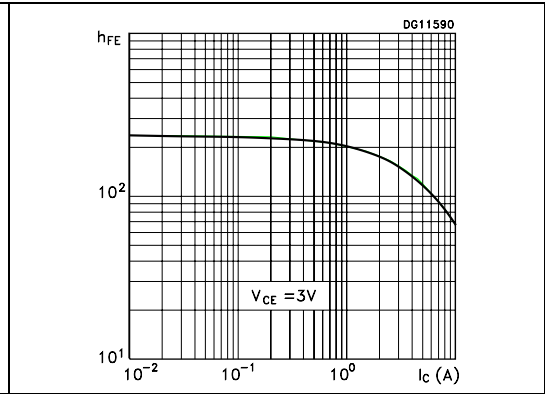


Figure 3. Collector-emitter saturation voltage

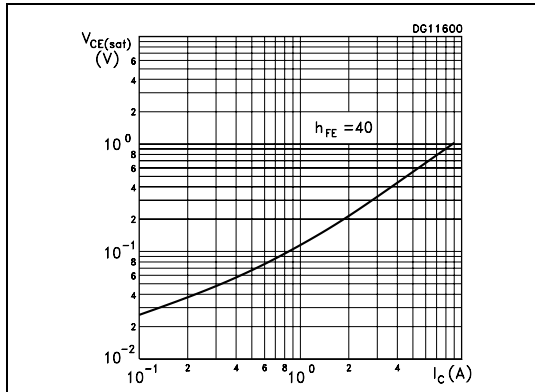


Figure 4. Base-emitter saturation voltage

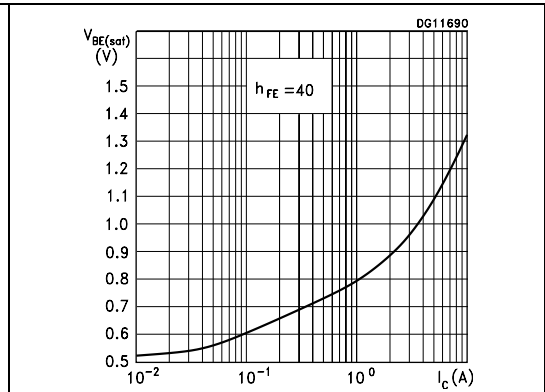


Figure 5. Switching time resistive load

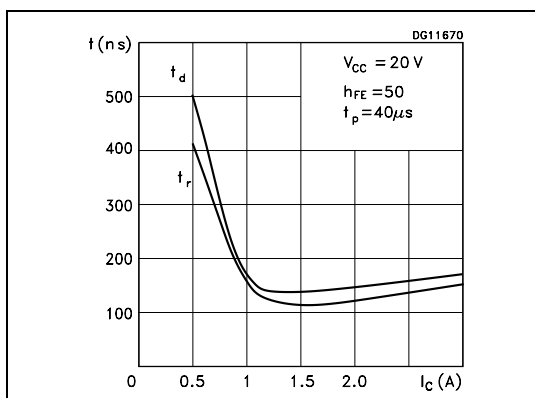
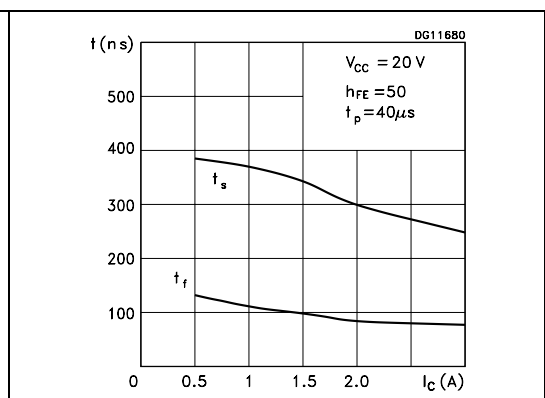
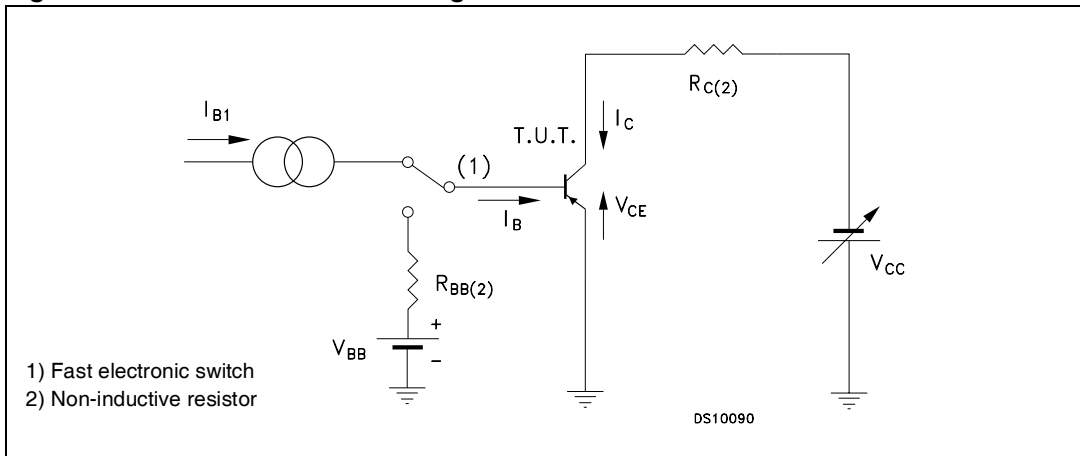


Figure 6. Switching time resistive load



## 2.2 Test circuits

Figure 7. Resistive load switching test circuit

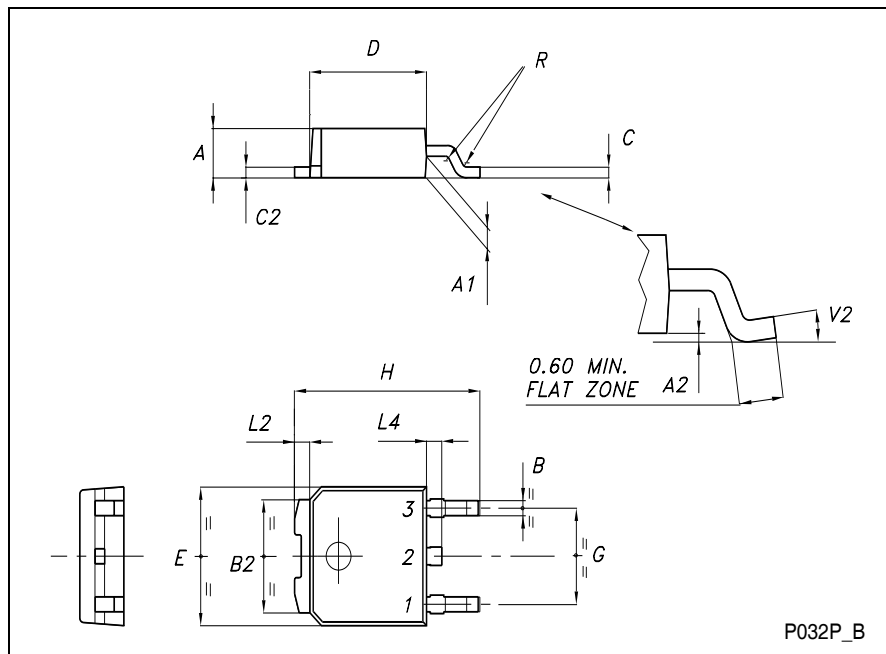


### 3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

**TO-252 (DPAK) MECHANICAL DATA**

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.213
C	0.45		0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.60	0.252		0.260
G	4.40		4.60	0.173		0.181
H	9.35		10.10	0.368		0.398
L2		0.8			0.031	
L4	0.60		1.00	0.024		0.039
V2	0°		8°	0°		0°





## 4 Revision history

Table 4. Revision history

Date	Revision	Changes
24-Mar-2004	1	Initial release.
03-Apr-2006	2	New template.

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